

CxO Summit

Opening Remarks

A. Manocha
President and CEO
SEMI, Milpitas, United States of America



Abstract

Opening Remarks

Biography

Throughout his career, Ajit Manocha has been a champion of industry collaboration as a critical means of advancing technology for societal and economic prosperity. He has been adept at forming strong partnerships with customers, suppliers, governments, academia, and communities for these efforts. In his current role as President and CEO of SEMI, the global industry association serving the electronics manufacturing supply chain, Manocha has positioned the organization to tackle major challenges facing the industry by building up workforce development programs to address its growing talent shortage and lack of gender parity.

Previously, he held senior worldwide operations leadership roles at Philips Semiconductors (NXP) and Spansion before serving as President and CEO at GLOBALFOUNDRIES. He has served on the boards of SEMI, SIA, and GSA.

Manocha began his career as a research scientist at AT&T Bell Laboratories, where he was granted over a dozen patents related to semiconductor manufacturing processes that served as the foundation for modern microelectronics manufacturing.

Manocha was an advisor to President Obama on the Advanced Manufacturing Partnership Steering committee and on the President's Council of Advisors on Science and Technology (PCAST). In 2012, during his tenure at GLOBALFOUNDRIES, he was awarded the prestigious "EHS Achievement Award — Inspired by Akira Inoue" for his commitment and action on Environmental Health and Safety standards. Additionally, he has excelled in people development by teaching courses such as "Leadership by Example" and "Classroom to Cleanroom to Boardroom."

In December 2019, Manocha was named an "All Star of the Semiconductor Industry" by VLSI Research for his visionary leadership in restructuring SEMI from its traditional position to represent the expanded electronics supply chain. In February 2020, he was inducted into the Silicon Valley Engineering Hall of Fame.

References

Welcome Remarks

L. Altimime
President
SEMI Europe, Berlin, Germany



Abstract

Welcome Remarks

Biography

Laith Altimime, as President of SEMI Europe, leads SEMI's activities in Europe and the Middle East and Africa (EMEA). Altimime has P&L responsibility as well as ownership of all Europe region programs and events, including SEMICON Europa. He is responsible for establishing industry standards, advocacy, community development, expositions, and programs. He provides support and services to SEMI members worldwide that have supply chain interests in Europe. He manages and nurtures relationships with SEMI members in the region and globally as well as with local associations and constituents in industry, government, and academia. Altimime has more than 30 years of international experience in the semiconductor industry. Prior to joining SEMI in 2015, He held senior leadership positions at NEC, KLA-Tencor, Infineon, Qimonda, and imec. Altimime holds an MSc from Heriot-Watt University, Scotland.

References

It's Time to Futureproof our Prosperity by Superfueling Innovation, Enabling Next-Gen AI

L. Van den hove
President & CEO
imec, Leuven, Belgium



Abstract

The AI field is evolving at an incredibly fast pace, with major models and updates being released almost every month. As these models evolve beyond Large Language Models towards next-gen AI with advanced reasoning capabilities, compute systems struggle to handle the heterogeneous workloads in a performant and sustainable way. However, developing new, AI-optimized compute architectures and the enabling semiconductor technologies takes much more time than writing algorithms. To prevent bottlenecks slowing down AI-based advancements, we must reinvent compute architectures and semiconductor technology platforms.

The presentation will shed light on the need for flexible, versatile compute architectures implemented in flexible, versatile technology platforms while addressing the increasing challenges of density, power and memory. To speed up both advanced semiconductor technology R&D and full stack innovation for future AI applications, imec is expanding its pilot line infrastructure under the EU Chips Act. Next to new infrastructure, imec aims to boost innovation through intensified collaborations with complementary knowledge partners and through further internationalization, attracting global talent and building strong, local ecosystems for diverse application domains, like health and automotive.

Transformative innovations for humankind hinge on the innovation pace of the semiconductor industry. It's time to supercharge our innovation engine, it's time to futureproof our prosperity.

Biography

Luc Van den hove is President and CEO of imec since July 1, 2009. Before he was executive vice president and chief operating officer. He joined imec in 1984, starting his research career in the field of silicide and interconnect technologies.

In 1988, he became manager of imec's micro-patterning group (lithography, dry etching); in 1996, department director of unit process step R&D; and in 1998, vice president of the silicon process and device technology division. In January 2007, he was appointed as imec's EVP & COO. Luc Van den hove received his PhD in electrical engineering from the KU Leuven, Belgium.

In 2023, he was honored with the Robert N. Noyce medal for his leadership in creating a worldwide research ecosystem in nanoelectronics technology with applications ranging from high-performance computing to health.

In 2025, he was awarded the honorary distinction from the Flemish Community in recognition of his impressive role in strengthening Flanders as a leading innovative region.

He has authored or co-authored more than 200 publications and conference contributions.

References

Topic Coming Soon

G. Avice Huet
Executive Vice President of Europe Operations
Schneider Electric, Paris, France



Abstract

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Biography

Gwenaëlle Avice Huet has been Schneider Electric's Executive Vice President of Europe Operations since September 4, 2023 and serves on its Executive Committee. She is responsible for Schneider Electric's full business portfolio across Europe Operations, representing the company's contribution to the development of the EU's agenda to accelerate Europe's green and digital transformation.

Gwenaëlle joined Schneider Electric in 2021 as Senior-Vice President of Corporate Strategy, before entering the Executive Committee as Chief Strategy and Sustainability Officer.

Before joining Schneider Electric, Gwenaëlle worked at ENGIE (formerly GDF SUEZ) in various roles, from Senior Vice-President of European and Regulatory affairs, to leading the Renewables energy business. In her last role, she was on the Executive Committee of ENGIE, serving as the Chief Executive Officer of ENGIE North America and in charge of the Global Business Line on Renewable Energies.

Gwenaëlle started her career at the French National Centre for Scientific Research and the French Atomic Energy Commission on nuclear energy before joining the World Bank in Washington D.C. as a consultant. She also worked for the service of the French Prime Minister within the General Secretary of European affairs with responsibility for energy and competitiveness matters, and as the advisor on energy and climate change for various ministers.

Gwenaëlle also serves on the Board of Air France – KLM. She holds a degree in Physics and Chemistry from the Ecole Normale Supérieure Paris-Saclay, a post-graduate diploma in Molecular Chemistry from France's Ecole Polytechnique and an engineering degree from the Corps des Ponts et Chaussées. She has also been nominated as a Young Global Leader by the World Economic Forum. She is based in Europe.

References

Topic Coming Soon

H. Blaschitz
Executive VP of Advanced Technology Facilities
Exyte, Singapore, Singapore



Abstract

Coming Soon

Biography

Herbert Blaschitz, Executive VP of Advanced Technology Facilities at Exyte, is a recognized leader in the semiconductor industry. He has played a pivotal role in the profitable expansion of Exyte's semiconductor business, growing it from 1 billion euros in 2014 to over 6 billion euros in 2023.

Before joining Exyte, he held various positions at Jenoptik, Asyst, and Siemens Semiconductor (now Infineon). Originally from Austria, Herbert has lived and worked in Germany, France, the USA, and currently resides in Singapore.

Herbert Blaschitz earned a degree in electrical engineering from HTBL of Klagenfurt, Austria, and a degree in business administration from GSBA in Zurich, Switzerland.

References

Topic Coming Soon

C. Koitzsch
President and Managing Director
European Semiconductor Manufacturing
Company (ESMC), Dresden, Germany



Abstract

Coming Soon

Biography

Dr. Christian Koitzsch has been the president and managing director of the European Semiconductor Manufacturing Company (ESMC) since beginning of 2024. He was raised in Thuringia, is married and is father of two children. He studied Electrical Engineering at Technische Universität Ilmenau and North Carolina State University in Raleigh (US) and received a PhD in solid state physics from the University of Neuchâtel, Switzerland.

References

From Atoms to Algorithms: European Suppliers' Technological Race to Stay Ahead in the Semiconductor Market

A. Grede
CTO
Comet, Geneva, Switzerland



Abstract

The semiconductor industry is accelerating into a new era, where breakthroughs are measured not only in nanometers but in the intelligence of entire systems. From the atomic scale of advanced materials to the power of algorithms in manufacturing and AI, the pace of change is relentless.

For European suppliers, the stakes have never been higher. Global rivals are scaling fast, customers are insourcing more than ever, and complexity itself has become the ultimate competitive edge.

In this environment, suppliers can no longer rely on products alone. Relevance will come from anticipating what customers need before they ask, being the trusted partner when complexity turns into risk, and unlocking the power of data to create intelligence that shapes the next generation of solutions.

Comet's CTO André Grede will chart the landscape ahead and invite us to rethink how European suppliers can turn today's pressure into tomorrow's advantage turning customer trust, early collaboration, and data-driven insight into their strongest competitive advantages.

Biography

André Grede is a seasoned technology leader with a deep background in electrical engineering and a passion for driving innovation in the semiconductor industry. He graduated in Electrical Engineering (Diplom-Ingenieur), specializing in high-frequency technology, from the Berlin Institute of Technology, where he began his career as a research associate in electrodynamics.

In 2011, André joined TRUMPF Hüttinger in Freiburg as a Team Leader in R&D, later advancing to Head of the RF Product Development Group. His expertise in radiofrequency (RF) technologies brought him to Comet in 2015, where he served as Vice President of Global R&D and Technology for Plasma Control Technologies. In this role, he shaped the division's technology and product roadmap for RF subsystems, a cornerstone of modern semiconductor manufacturing.

Since 2023, André has been serving as Chief Technology Officer of Comet Group. With his pioneering spirit and forward-looking vision, he is driving the company's transformation from a manufacturing-centered organization to one that fully integrates software and digital intelligence, positioning Comet as a key partner in the fast-evolving semiconductor landscape.

References

Topic Coming Soon

J. Schulze
Spokesperson for the Bavarian Chips Alliance,
Director of the Fraunhofer IISB
Bayern Innovativ GmbH, Munich, Germany



Abstract

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Biography

Experienced Semiconductor Physicist and Engineer with a demonstrated history of working in the research industry and academia. Skilled in Research and Development (R&D) for semiconductor-based Micro, Nano, Opto, Power, Quantum Electronics. Experienced Lecturer and Teacher in Experimental Physics, Semiconductor Physics-Engineering-Technolog

References

Topic Coming Soon

T. Gan
Executive Director
Institute of Microelectronics, Singapore,
Singapore



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C. Frey
Vice-President of EU Engagements & General
Manager
Arm France, Sophia Antipolis, France



Abstract

Coming Soon

Biography

Based in Sophia Antipolis France, he has been the **General Manager of Arm France** since 2014. He also serves as **VP of EU Engagements** where he focuses on strengthening Arm's presence within the European semiconductor ecosystem.

Prior to Arm he has held various roles in design and management at STMicroelectronics in Crolles, France, for 12 years. He contributed to establish the Crolles2 alliance with Philips and Motorola, an experience that led to his first international immersion in Austin Texas.

He then joined the startup SOISIC, where he served as VP of Engineering before the company was acquired by Arm in 2006. At Arm, he has spent four years in Silicon Valley California as VP of Operations.

In 2024 he became an operating Partner at C4 Ventures investment fund, where he brings his 30 years of experience in the semiconductor industry.

He holds a MS degree from PHELMA Grenoble.

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Topic Coming Soon

F. Gualandris
President Quality, Manufacturing & Technology
STMicroelectronics, Milan, Italy



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Biography

Fabio Gualandris is STMicroelectronics' President, Quality, Manufacturing, and Technology and has held this position since July 2023. He was responsible for the company's Back-End Manufacturing & Technology organization since 2016 and also led the Company's Testing Council, alongside its manufacturing strategy in Asia and efforts in System-in-Package technology. Gualandris is a member of ST's Executive Committee.

Gualandris joined SGS Microelettronica (now ST) R&D in 1984. He became R&D Director of Operations in 1989 and became Automotive BU Director in 1996. After two years as President and CEO of Semitool, he rejoined ST in 2000 as Group VP responsible for memory products including the RAM/PSRAM and Automotive Flash.

In 2005, Gualandris was appointed CEO of ST Incard, an ST smart-card subsidiary. In 2008-2010, he served as VP and Supply Chain General Manager at ST's memory JV with Intel. In 2011, Gualandris was appointed ST's Executive Vice President, Product Quality Excellence. Gualandris has authored several technical and managerial papers and holds multiple international patents. He serves as Chairman of STS, ST's manufacturing JV in China.

Fabio Gualandris was born in Bergamo, Italy, in 1959. He holds a Master's degree in Physics from the University of Milan.

References

Topic Coming Soon

A. Hidma
Senior Vice President EUR & US
ASML, Delft, The Netherlands



Abstract

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Biography

Anne is responsible for ASML's customer and research partnerships, as well as business operations across these regions.

As such, Anne's team addresses customers' future technology roadmaps, application challenges, and operational requirements.

Next to the financial and operational management of our customer business, she drives improvements in ASML's products and services together with the broader ASML organization to better meet customer needs.

Anne is a member of the Executive Team of ASML.

Prior to ASML, Anne was a Partner at McKinsey & Company. She led the Advanced Industries practice in the Benelux and was a core part of the Strategy & Corporate Finance practice in Europe.

Anne obtained her MSc degree in Nanoscience at the faculty Applied Physics of Delft University of Technology. She holds an MBA degree from Columbia University in New York.

References

Topic Coming Soon

M. Horstmann
General Manager and Senior Vice President
GlobalFoundries, Dresden, Germany



Abstract

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Biography

Manfred Horstmann serves as General Manager and Senior Vice President at GlobalFoundries (GF), overseeing European fabs, including GF's 300mm manufacturing facility in Dresden. He also leads the GlobalFoundries Engineering Services (GFES) teams in Singapore, Penang, Bangalore, and Malaysia, supporting GF's global manufacturing operations.

Since 2020, he has transformed the Dresden Fab cluster into Europe's largest 300mm wafer facility, achieving a two and a half output increase in less than three years, boosting productivity and strategically optimizing operations. He and his team led the development and production of a highly differentiated technology portfolio (55nm-22nm) for applications in fast growing markets such as automotive, MCUs, display drivers, audio amplifiers, security chip cards, radio frequency (RF) and 5G technology.

With over 27 years of experience in multiple leadership positions in spanning research, technology development, product engineering, and large-scale operations, Mr. Horstmann has held leadership roles at Advanced Micro Devices (AMD), Motorola, and IBM in Germany and the United States.

Mr. Horstmann holds over 100 patents, has authored more than 200 scientific papers and serves on advisory boards for Forschungszentrum Jülich and Nanoelectronic Materials Laboratory. Mr. Horstmann earned his Diploma and PhD in Physics from Rheinisch-Westfälische Technische Hochschule (RWTH) Aachen.

References